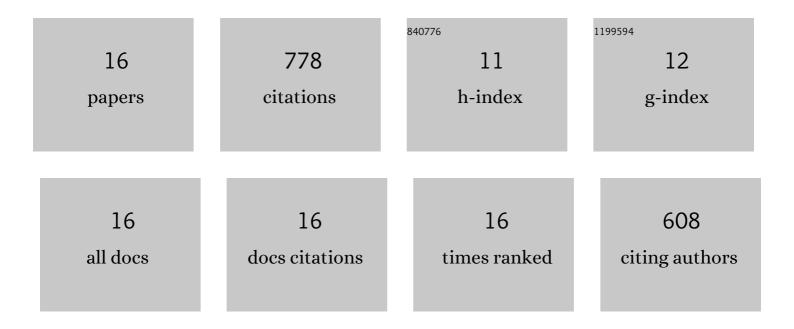
James P Mcvittie

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/11745938/publications.pdf Version: 2024-02-01



#	Article	IF	CITATIONS
1	Ge-Interface Engineering With Ozone Oxidation for Low Interface-State Density. IEEE Electron Device Letters, 2008, 29, 328-330.	3.9	172
2	A tuned Langmuir probe for measurements in rf glow discharges. Journal of Applied Physics, 1990, 67, 6718-6727.	2.5	154
3	Simulation of profile evolution in silicon reactive ion etching with re-emission and surface diffusion. Journal of Vacuum Science & Technology an Official Journal of the American Vacuum Society B, Microelectronics Processing and Phenomena, 1992, 10, 1091.	1.6	133
4	A twoâ€dimensional computer simulation for dry etching using Monte Carlo techniques. Journal of Applied Physics, 1989, 65, 1484-1491.	2.5	73
5	Charging damage to gate oxides in an O2magnetron plasma. Journal of Applied Physics, 1992, 72, 4865-4872.	2.5	69
6	Core-Shell Germanium/Germanium–Tin Nanowires Exhibiting Room-Temperature Direct- and Indirect-Gap Photoluminescence. Nano Letters, 2016, 16, 7521-7529.	9.1	54
7	Model for oxide damage from gate charging during magnetron etching. Applied Physics Letters, 1993, 62, 1507-1509.	3.3	30
8	lon trajectory distortion and profile tilt by surface charging in plasma etching. Applied Physics Letters, 1994, 64, 1558-1560.	3.3	29
9	Crystalâ€Orientation Dependent Etch Rates and a Trench Model for Dry Etching. Journal of the Electrochemical Society, 1988, 135, 1521-1525.	2.9	27
10	Integrating Phase-Change Memory Cell With Ge Nanowire Diode for Crosspoint Memory—Experimental Demonstration and Analysis. IEEE Transactions on Electron Devices, 2008, 55, 2307-2313.	3.0	20
11	Scaling laws for radio frequency glow discharges for dry etching. Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films, 1990, 8, 1654-1662.	2.1	11
12	In-Situ Monitoring of Electrical Parameters for Dry Etching. Materials Research Society Symposia Proceedings, 1987, 98, 203.	0.1	4
13	NEM relays using 2-dimensional nanomaterials for low energy contacts. , 2013, , .		2
14	The Role of "Antenna―Structure on Thin Oxide Damage from Plasma Induced Wafer Charging. Materials Research Society Symposia Proceedings, 1992, 265, 231.	0.1	0
15	Limitations of Plasma Charging Damage Measurements Using MOS Capacitor Structures. Materials Research Society Symposia Proceedings, 1996, 428, 349.	0.1	0
16	Plasma induced wafer charging sensor. Journal of the Chinese Institute of Engineers, Transactions of the Chinese Institute of Engineers,Series A/Chung-kuo Kung Ch'eng Hsuch K'an, 1998, 21, 11-19.	1.1	0